

## PATENT ABSTRACTS OF JAPAN

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## (54) SOLID-STATE IMAGE PICKUP DEVICE AND ITS MANUFACTURE

(57)Abstract:

PROBLEM TO BE SOLVED: To attain a remarkably thin profile in a way that a height of a solid-state image pickup element unit is substantially equal to a maximum thickness of a mounted printed circuit board because the thickness of the mount printed circuit board is thicker when the solid-state image pickup element unit is mounted on one side of the printed circuit board in the solid-state image pickup device.

SOLUTION: A solid-state image pickup element unit 11 is assembled with a CCD chip 12 whose one major side has a light receiving face 12a, a film carrier 13 that propagates input output signals of the CCD chip 12, and an image pickup optical system consisting of a lens 17 that forms light incident onto the CCD chip 12 and of a light transmission member 15 such as an optical filter. The solid-state image pickup element unit 11 is inserted to an opening 18a provided to part of a printed circuit board 18 on which electronic components 19 mounted and the unit 11 is fixed at a position at which the thickness of the mounted printed circuit board is minimized.

